

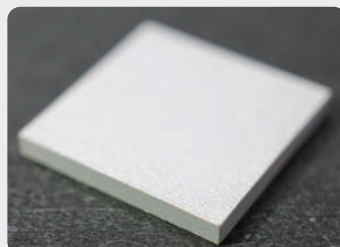
EMI Shielding Paste

Spraying directly onto semiconductor packages

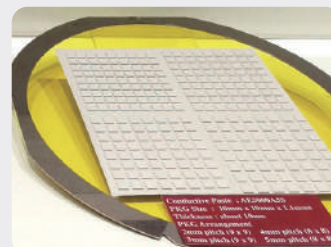
Applications

Semiconductor packages

Thin conductive paste layer on 3D surfaces by spray coating.
Low cost solution compared to sputtering.



After deposition and curing



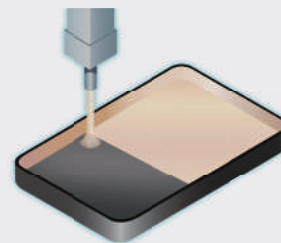
After deposition and curing

Housing

Deposit to electronics device plastic housing by spray coating.



After deposition and curing



Spray coating

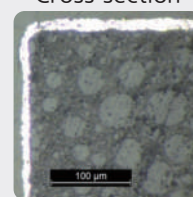
Features

- Excellent shielding effectiveness over 70 dB
- Excellent adhesion to various surfaces
- Low cost solution compared to sputtering
- Applicable to low frequency range shielding

Surface of coated PKG



Cross-section



Product line-up & properties

Product			AE5000A5-12GS	AE5000W Series	AE5000L-73
Type			For semiconductor packages		
Filler	Conductive particles		Silver	Silver coated copper	
	Average particle size	μm	3 - 5	4 - 6	3 - 5
Binder	Resin		Epoxy		
Viscosity	BH type	dPa·s	15 - 25	10 - 50	0 - 20
Density		g/cm ³	2.5 - 3.1	2.7 - 3.3	2.5 - 3.1
Curing conditions	Pre-curing		100°C × 10min.		
	Post-curing		170°C × 50min.	150°C × 50min.	100°C × 60min.
Volume resistivity (Representative value)		Ω·cm	5.0E-05	2.0E-05	1.0E-04
Shelf-life	-20°C	month(s)	6.0	2.0	3.0
	-40°C	month(s)	12.0	4.0	6.0

